

V_{DM}	=	2800 V
$I_{T(AV)M}$	=	2630 A
$I_{T(RMS)}$	=	4130 A
I_{TSM}	=	43×10^3 A
V_{TO}	=	0.85 V
r_T	=	0.16 mW

Bi-Directional Control Thyristor

5STB 24Q2800

Doc. No. 5SYA1053-02 May 07

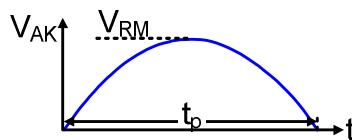
- Two thyristors integrated into one wafer
- Patented free-floating silicon technology
- Designed for energy management and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

The electrical and thermal data are valid for one-thyristor-half of the device (unless otherwise stated)

Blocking

Maximum rated values¹⁾

Parameter	Symbol	Conditions	5STB 24Q2800	Unit
Max repetitive peak forward blocking voltage	V_{RM}	$f = 50$ Hz, $t_p = 10$ ms, $T_{vj} = 5 \dots 125^\circ\text{C}$, Note 1	2800	V
Critical rate of rise of off-state voltage	dv/dt_{crit}	Exp. to 1880 V, $T_{vj} = 125^\circ\text{C}$	1000	V/ μ s



Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Max reverse leakage current	I_{RM}	V_{RM} , $T_{vj} = 125^\circ\text{C}$			400	mA

Note 1: Voltage de-rating factor of 0.11% per $^\circ\text{C}$ is applicable for T_{vj} below $+5^\circ\text{C}$

Mechanical data

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		81	90	108	kN
Acceleration	a	Device unclamped			50	m/s^2
Acceleration	a	Device clamped			100	m/s^2

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				2.1	kg
Housing thickness	H	$F_M = 90$ kN, $T_a = 25^\circ\text{C}$	25.8		26.4	mm
Surface creepage distance	D_S		36			mm
Air strike distance	D_a		15			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

ABB Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.



On-state

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	I _{T(AV)M}	Half sine wave, T _c = 70 °C			2630	A
RMS on-state current	I _{T(RMS)}				4130	A
RMS on-state current	I _{T(RMS)}	Full sine wave, T _c = 70°C t _p = 10 ms, T _{vj} = 125 °C, sine wave after surge: V _D = V _R = 0 V			5840	A
Peak non-repetitive surge current	I _{TSM}				43.0×10 ³	A
Limiting load integral	I ² t	t _p = 8.3 ms, T _{vj} = 125 °C, sine wave after surge: V _D = V _R = 0 V			9.25×10 ⁶	A ² s
Peak non-repetitive surge current	I _{TSM}				46.0×10 ³	A
Limiting load integral	I ² t				8.78×10 ⁶	A ² s

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V _T	I _T = 3000 A, T _{vj} = 125 °C			1.35	V
Threshold voltage	V _{T0}	I _T = 1500 A - 4500 A, T _{vj} = 125 °C			0.85	V
Slope resistance	r _T				0.16	mΩ
Holding current	I _H	T _{vj} = 25 °C			250	mA
		T _{vj} = 125 °C			150	mA
Latching current	I _L	T _{vj} = 25 °C			500	mA
		T _{vj} = 125 °C			300	mA

Switching

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	di/dt _{crit}	T _{vj} = 125 °C, I _{TRM} = 3000 A,	Cont.		250	A/μs
Critical rate of rise of on-state current	di/dt _{crit}		f = 50 Hz			
Circuit commutated turn-off time	t _q	T _{vj} = 125 °C, I _{TRM} = 2000 A, V _R = 200 V, di _T /dt = -1.5 A/μs, V _D ≤ 0.67·V _{RM} , dv _D /dt = 20 V/μs	400			μs
Critical rate of rise of commutating voltage	dv/dt _{com}	T _{vj} = 125 °C, V _R ≤ 0.67·V _{RM}			500	V/μs

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q _{rr}	T _{vj} = 125 °C, I _{TRM} = 2000 A, V _R = 200 V, di _T /dt = -1.5 A/μs	1000		2100	μAs
Reverse recovery current	I _{RM}		30		80	A
Gate turn-on delay time	t _{gd}	T _{vj} = 25 °C, V _D = 0.4·V _{RM} , I _{FG} = 2 A, t _r = 0.5 μs			3	μs

Triggering

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V _{FGM}				12	V
Max. rated peak forward gate current	I _{FGM}				10	A
Peak reverse gate voltage	V _{RGM}				10	V
Max. rated gate power loss	P _G	For DC gate current			3	W
Max. rated peak forward gate power	P _{GM(AV)}			see Fig. 9		W

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate trigger voltage	V _{GT}	T _{vj} = 25 °C			2.6	V
Gate trigger current	I _{GT}	T _{vj} = 25 °C			400	mA
Gate non-trigger voltage	V _{GD}	V _D = 0.4 x V _{RM} , T _{vj} = 125 °C	0.3			V
Gate non-trigger current	I _{GD}	V _D = 0.4 x V _{RM}	10			mA

Thermal

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T _{vj}				125	°C
Storage temperature range	T _{stg}		-40		140	°C

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case (Valid for one thyristor half no heat flow to the second half.)	R _{th(j-c)}	Double-side cooled F _m = 81...108 kN			10	K/kW
	R _{th(j-c)}	Single-side cooled F _m = 81...108 kN			20	K/kW
Thermal resistance case to heatsink	R _{th(c-h)}	Double-side cooled F _m = 81...108 kN			2	K/kW
	R _{th(c-h)}	Single-side cooled F _m = 81...108 kN			4	K/kW

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/t_i})$$

i	1	2	3	4
R _i (K/kW)	6.500	1.470	1.310	0.710
t _i (s)	0.5205	0.1075	0.0194	0.0073

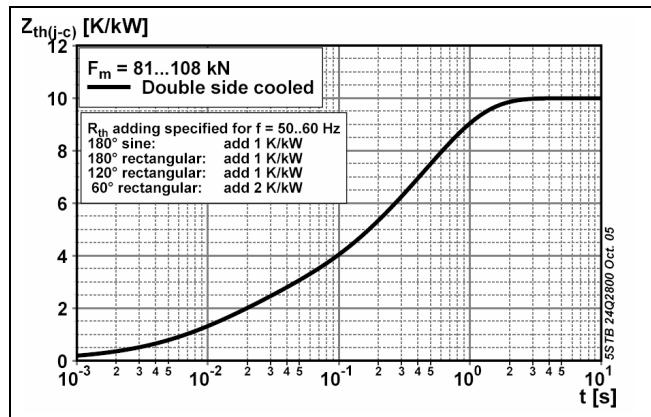
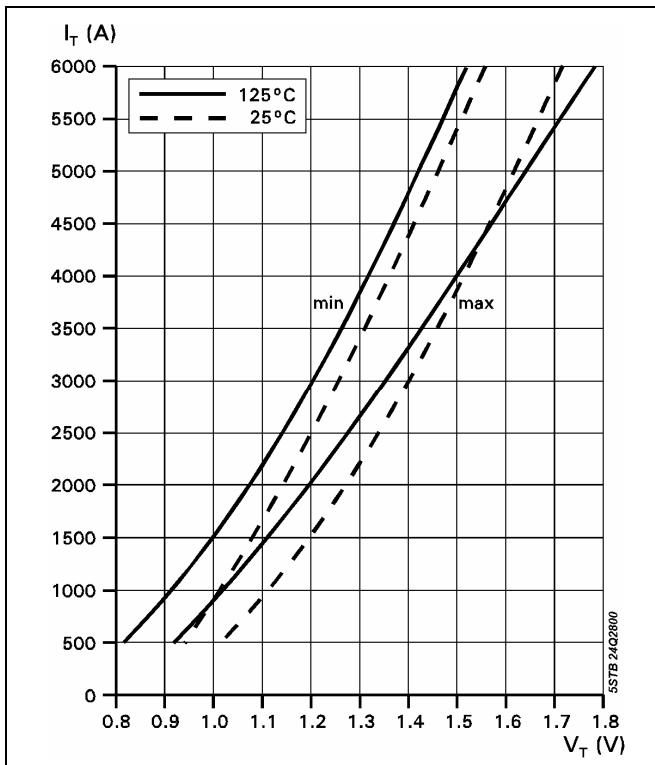
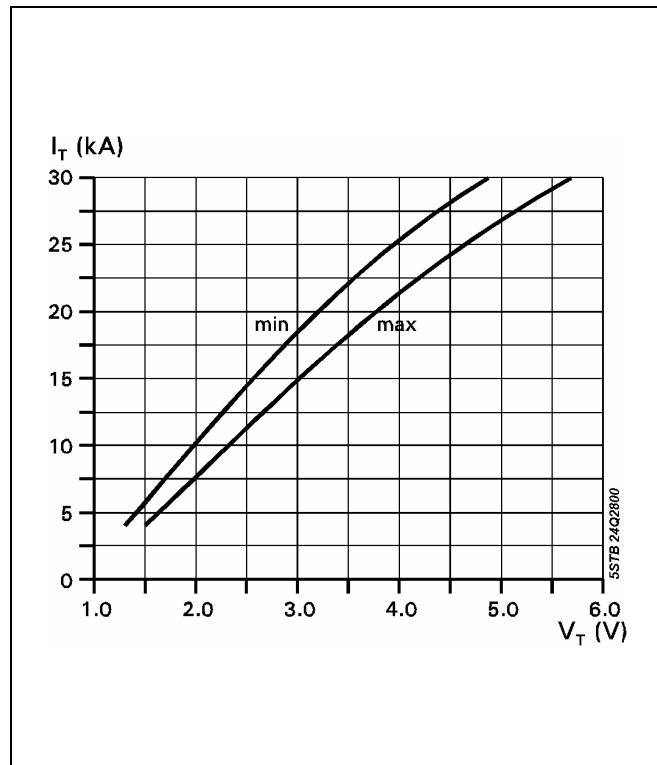
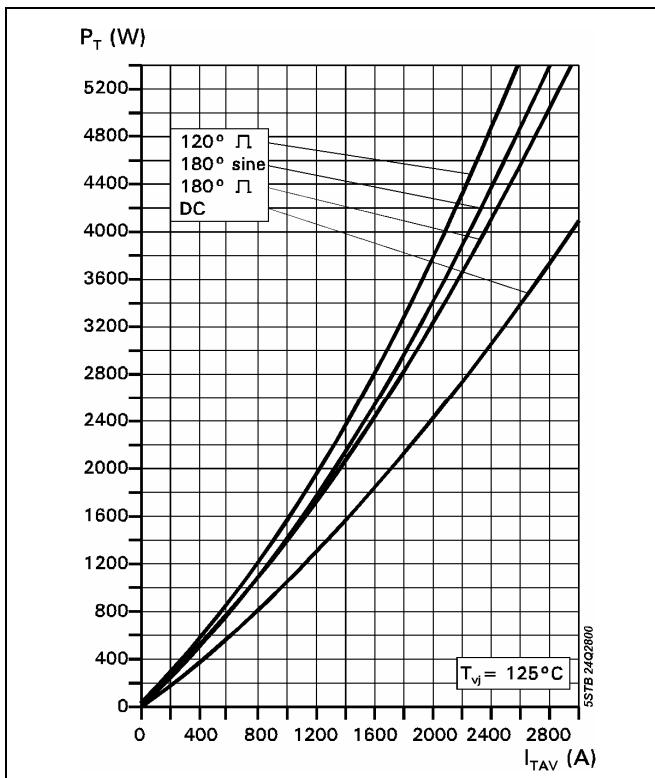
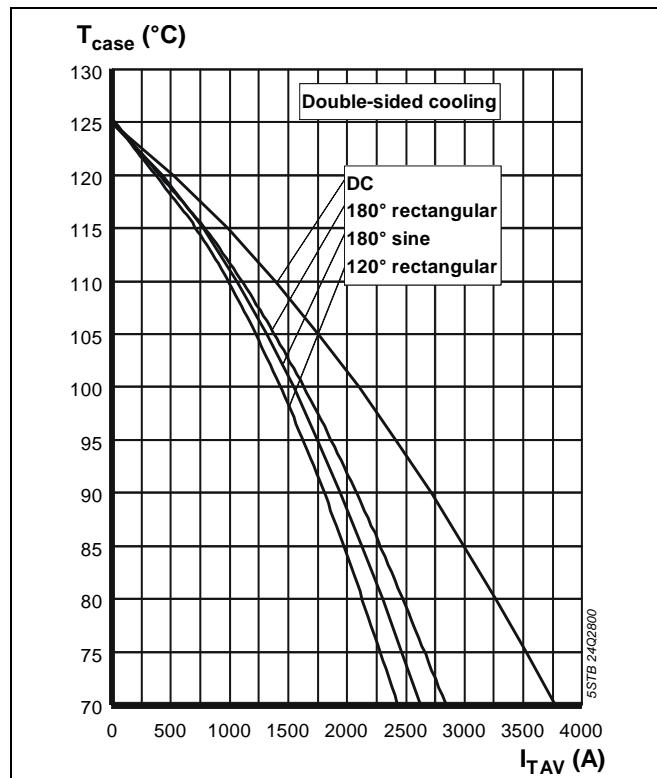
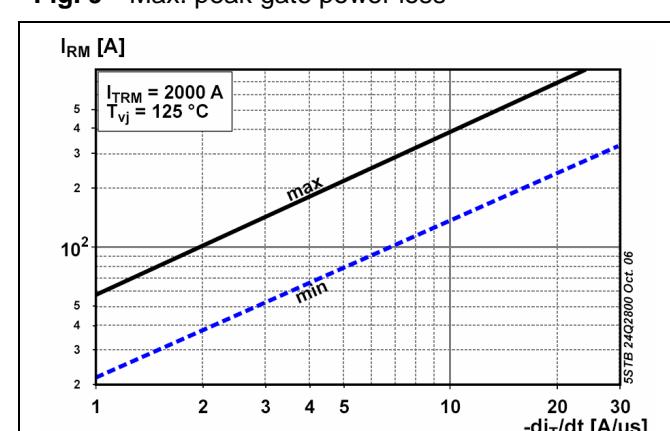
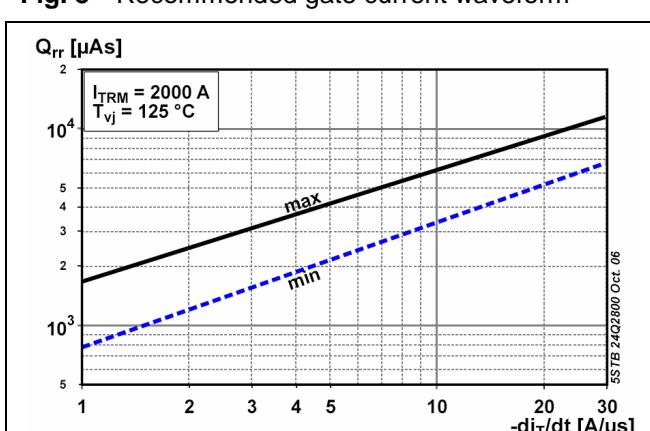
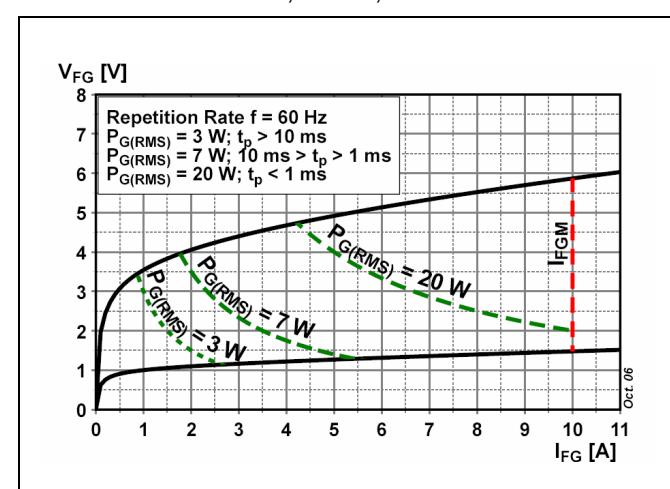
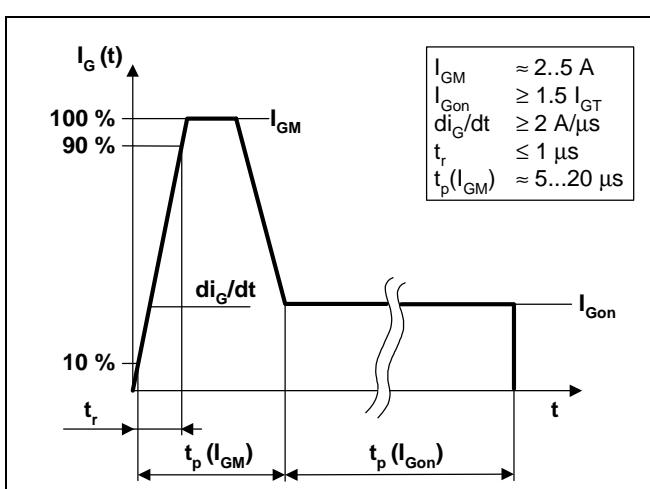
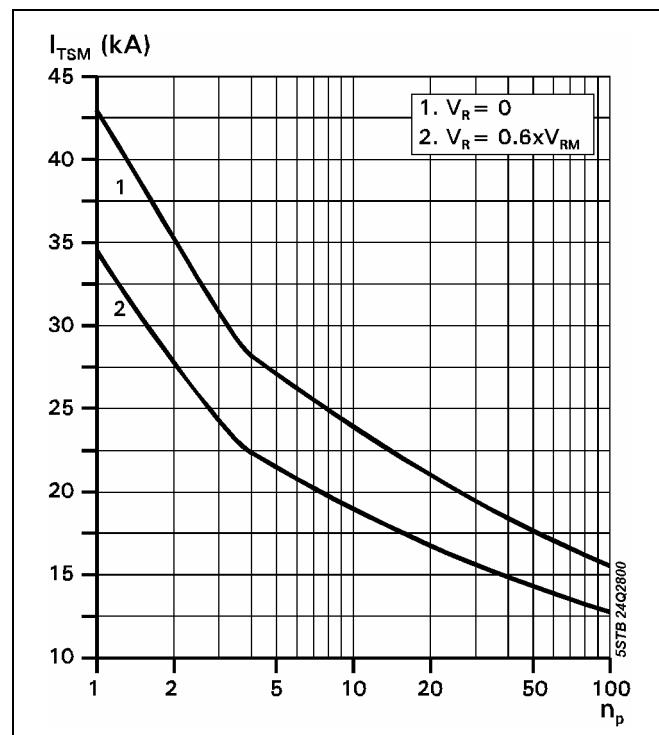
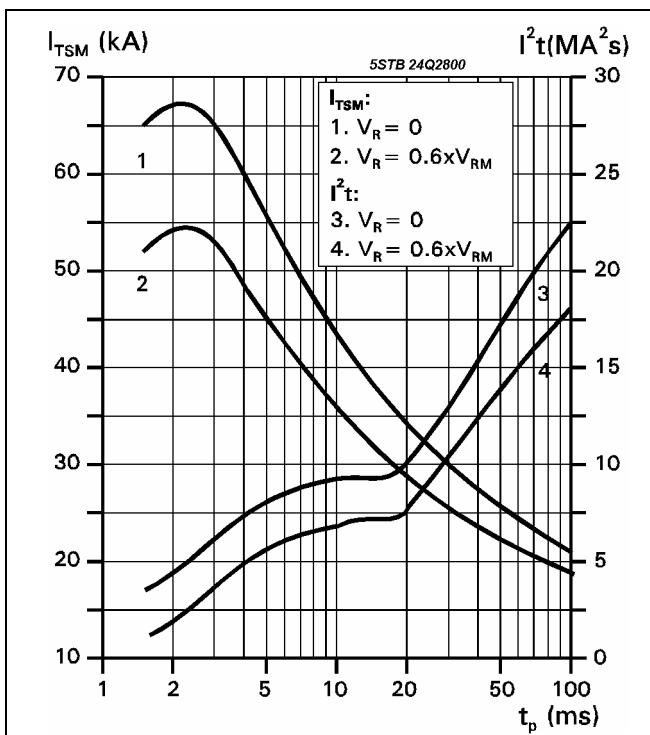


Fig. 1 Transient thermal impedance (junction-to-case) vs. time

**Fig. 2** On-state voltage characteristics**Fig. 3** On-state characteristics.
 $T_j = 125^\circ\text{C}$, 10ms half sine.**Fig. 4** On-state power dissipation vs. mean on-state current. Turn-on losses excluded.**Fig. 5** Max. permissible case temperature vs. mean on-state current. Switching losses ignored.



Turn-on and Turn-off losses

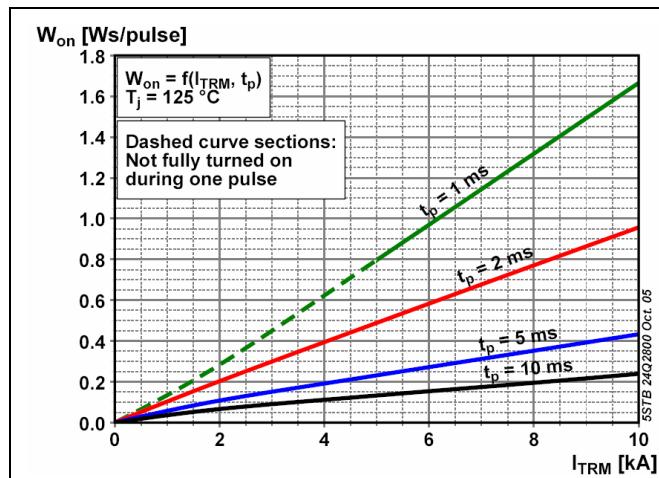


Fig. 12 Turn-on energy, half sinusoidal waves

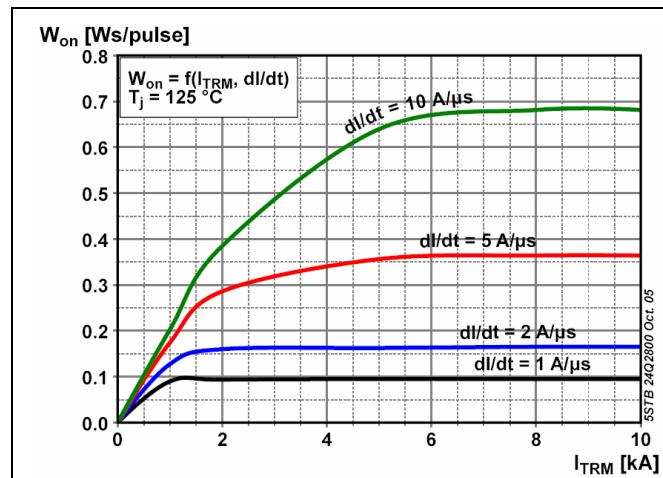


Fig. 13 Turn-on energy, rectangular waves

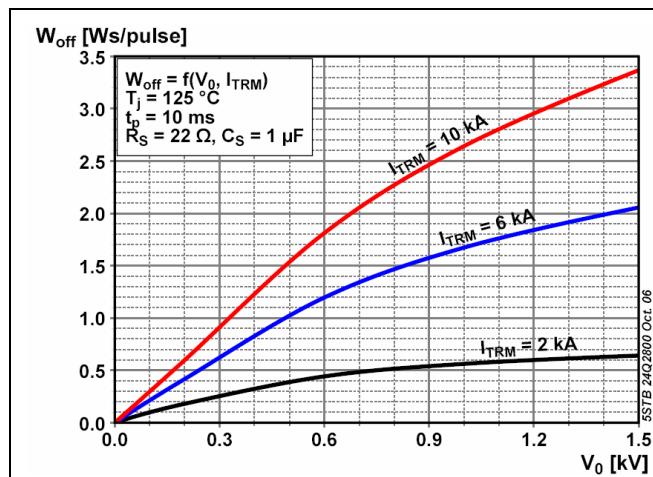


Fig. 14 Turn-off energy, half sinusoidal waves

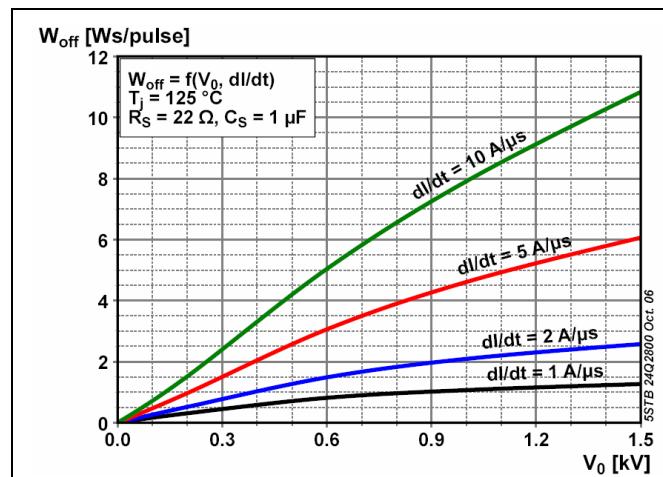


Fig. 15 Turn-off energy, rectangular waves

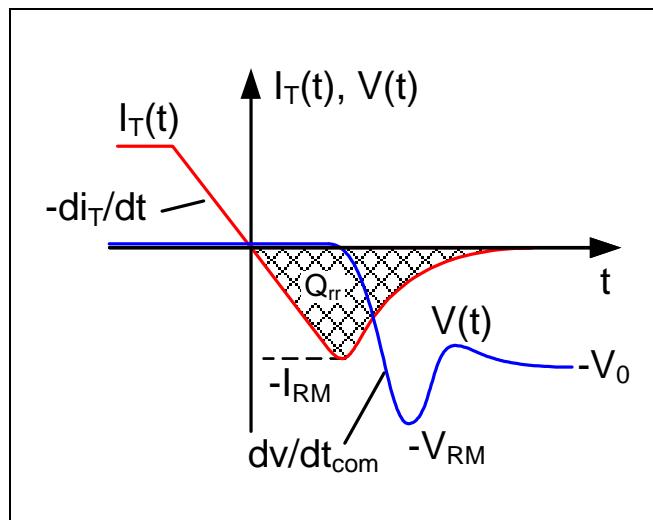


Fig. 16 Current and voltage waveforms at turn-off

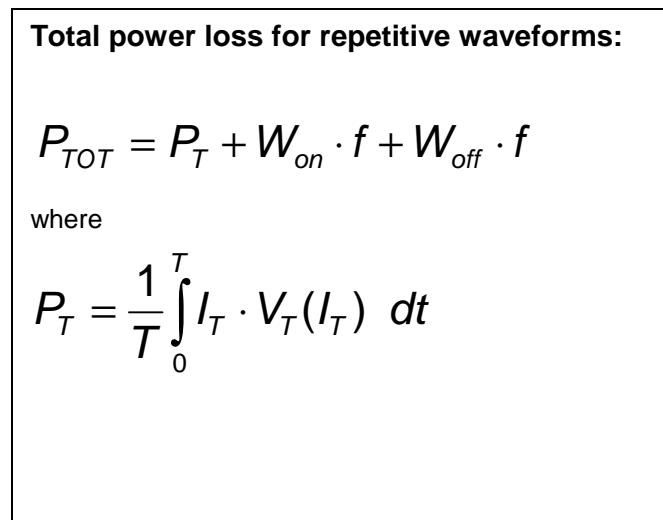


Fig. 17 Relationships for power loss

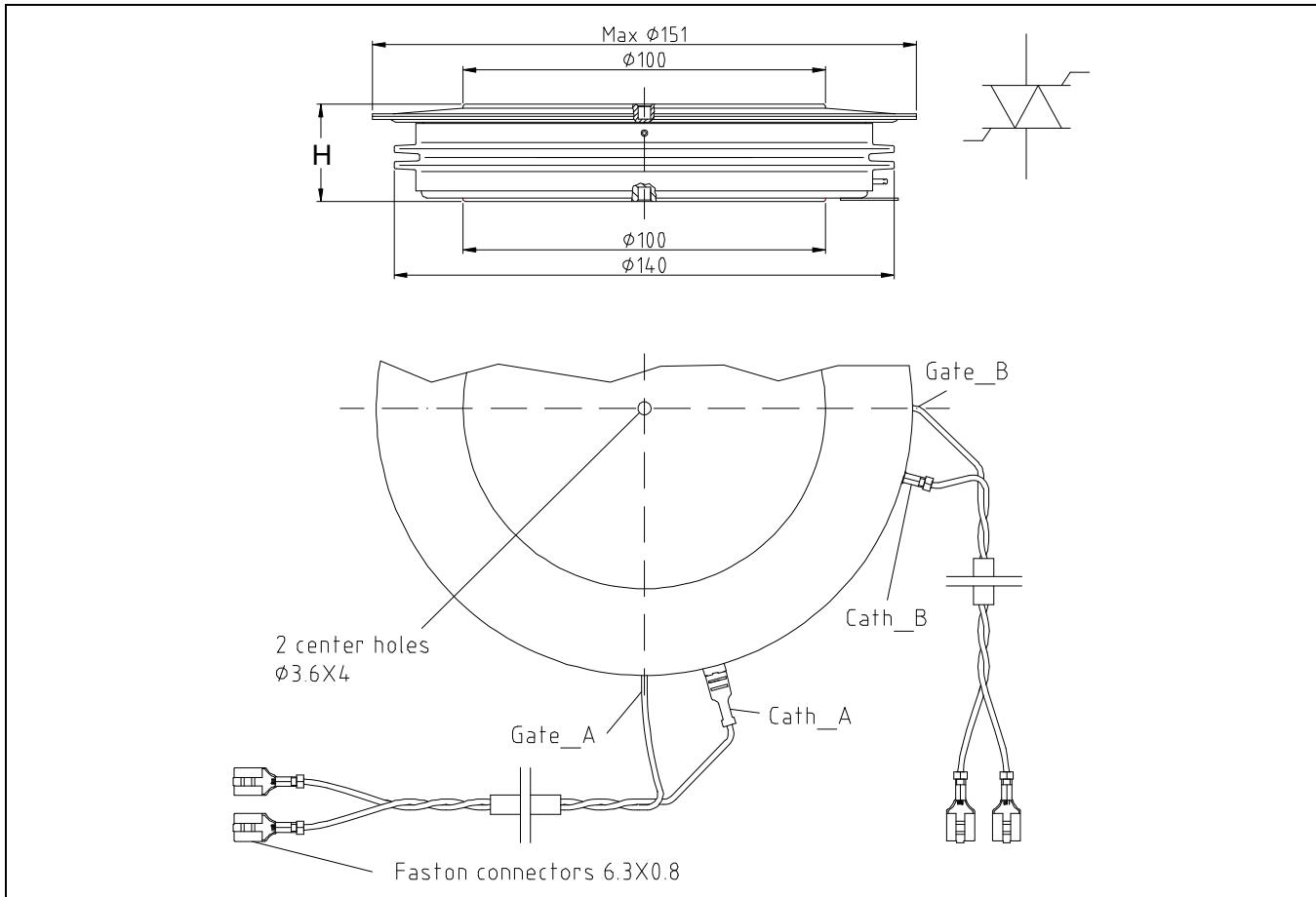


Fig. 18 Device Outline Drawing

Related documents:

-
- | | |
|-----------|---|
| 5SYA 2020 | Design of RC-Snubber for Phase Control Applications |
| 5SYA 2049 | Voltage definitions for phase control thyristors and diodes |
| 5SYA 2051 | Voltage ratings of high power semiconductors |
| 5SYA 2034 | Gate-Drive Recommendations for PCT's |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors |
| 5SZK 9104 | Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE available on request, please contact factory |
| 5SZK 9105 | Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION available on request, please contact factory |

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

ABB Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.



**ABB Switzerland Ltd
Semiconductors**
Fabrikstrasse 3
CH-5600 Lenzburg, Switzerland

Doc. No. 5SYA1053-02 May 07

Telephone +41 (0)58 586 1419
Fax +41 (0)58 586 1306
Email abbsem@ch.abb.com
Internet www.abb.com/semiconductors